

APBA3010SYKCGKC-GX

3.0 mm x 1.0 mm Right Angle SMD Chip LED Lamp

DESCRIPTIONS

- The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip
- . The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- . It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 3.0 x 2.0 x 1.0 mm right angle SMD LED, 1.0 mm thickness
- Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · Tinned pads for improved solderability
- · Halogen-free
- · RoHS compliant

APPLICATIONS

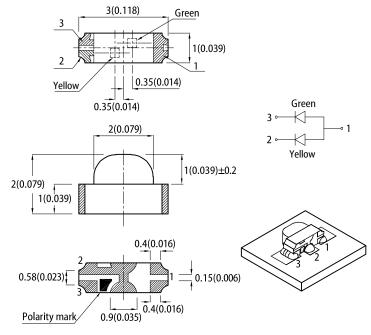
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

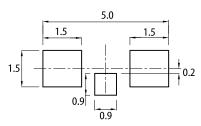


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



- Toles.

 1. All dimensions are in millimeters (inches).

 2. Tolerance is ±0.15(0.006") unless otherwise noted.

 3. The specifications, characteristics and technical data described in the datasheet are subject to
- The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
APBA3010SYKCGKC-GX	Super Bright Yellow (AlGaInP)	Water Clear	80	120	140°
	Green (AlGaInP)		40	70	140

Notes.
1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Тур.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Super Bright Yellow Green	590 574	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Super Bright Yellow Green	590 570	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Super Bright Yellow Green	20 20	-	nm
Capacitance	С	Super Bright Yellow Green	20 15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Super Bright Yellow Green	2.0 2.1	2.5 2.5	V
Reverse Current (V _R = 5V)	I _R	Super Bright Yellow Green	-	10 10	μΑ
Temperature Coefficient of λ_{peak} I _F = 20mA, -10°C \leq T \leq 85°C	TC _{λpeak}	Super Bright Yellow Green	0.12 0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 20mA, -10°C \leq T \leq 85°C	TC _{λdom}	Super Bright Yellow Green	0.07 0.08	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TC _V	Super Bright Yellow Green	-1.9 -1.9	-	mV/°C

Notes:

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Va	Unit	
		Super Bright Yellow	Green	
Power Dissipation	P _D	75	75	mW
Reverse Voltage	V_R	5	5	V
Junction Temperature	TJ	115	115	°C
Operating Temperature	T _{op}	-40 To +85		°C
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	30	mA
Peak Forward Current	I _{FM} ^[1]	175	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	680	670	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	580	560	°C/W

Notes:
1. 1/10 Duty Cycle, 0.1 ms Pulse Width.
2. $R_{\text{th JS}}$ Results from mounting on PC board FR4 (pad size \geq 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)

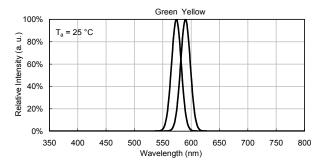
^{2.} Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.

^{4.} Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

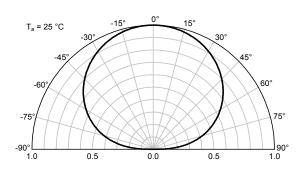


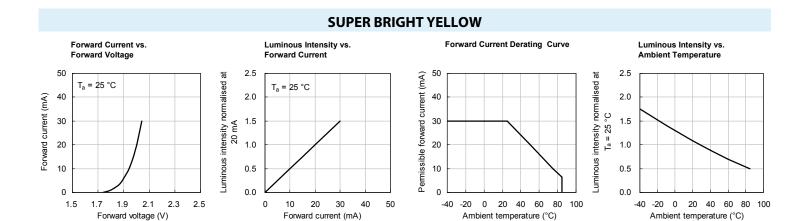
TECHNICAL DATA

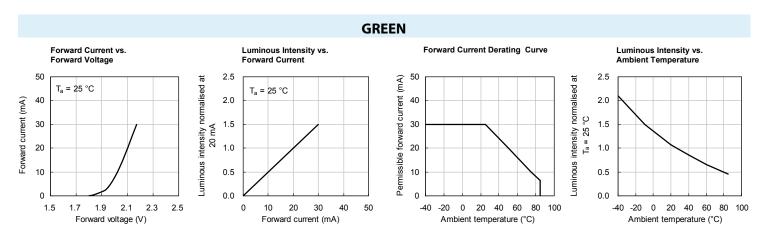
RELATIVE INTENSITY vs. WAVELENGTH



SPATIAL DISTRIBUTION

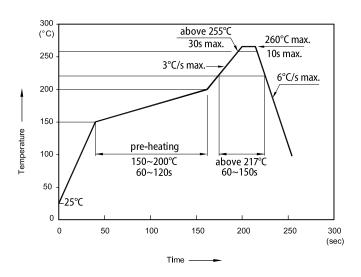






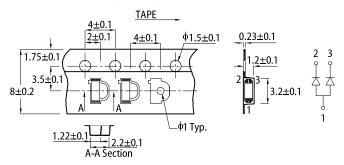


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

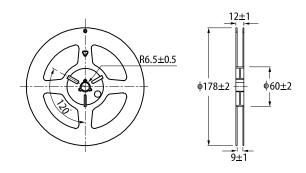


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

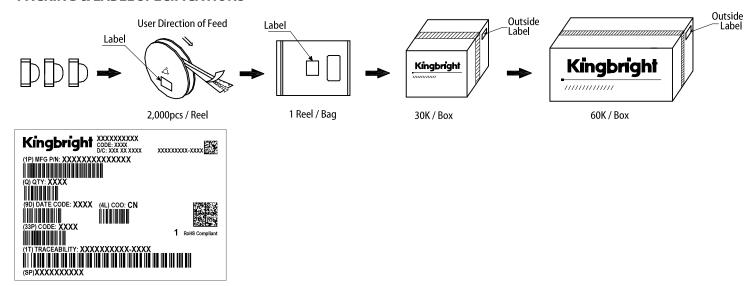
TAPE SPECIFICATIONS (units: mm)



REEL DIMENSION (units: mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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